

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

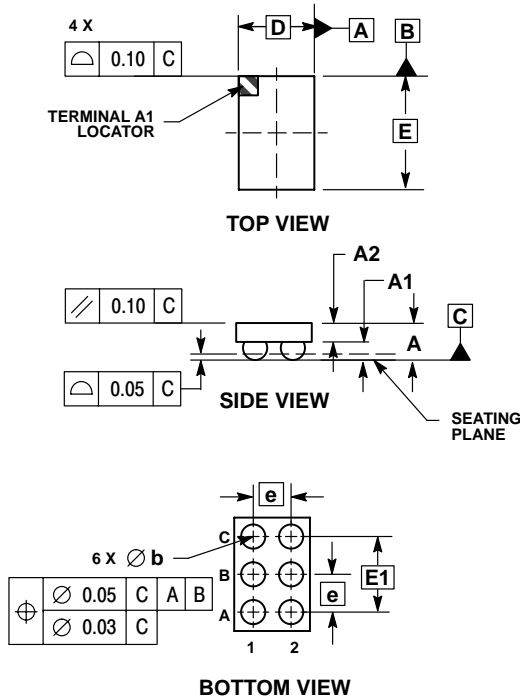
ON Semiconductor®



A1  
SCALE 4:1

6 PIN FLIP-CHIP  
CASE 499AH-01  
ISSUE O

DATE 19 APR 2004

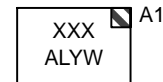


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.448	0.533
A1	0.210	0.270
A2	0.238	0.263
D	1.000 BSC	
E	1.50 BSC	
b	0.290	0.340
e	0.500 BSC	
E1	1.000 BSC	

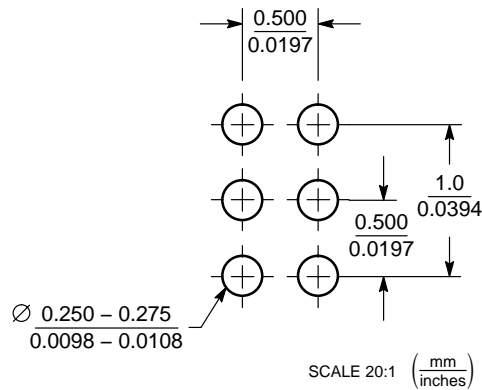
**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code  
 A = Assembly Location  
 L = Wafer Lot  
 Y = Year  
 W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>6 PIN FLIP-CHIP, NCP400, 1.00 X 1.5 MM, 0.50 MM PITCH</b>	<b>PAGE 1 OF 2</b>

